

Specifications

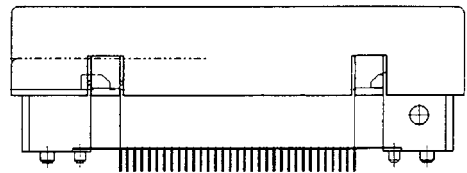
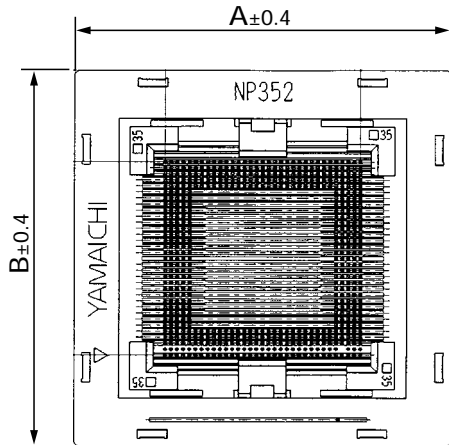
Insulation Resistance: 1,000MΩ min. at 100V DC
 Dielectric Withstanding Voltage: 100V AC for 1 minute
 Contact Resistance: 100mΩ max. at 10mA/20mV max.
 Operating Temperature Range: -40°C to +150°C / -55°C to +150°C
 Contact Force: 15g per pin approx.
 Mating Cycles: 10,000 insertions minimum



Materials and Finish

Housing: Polyetherimide (PEI), glass-filled
 Polyethersulphone (PES), glass-filled
 Contacts: Beryllium Copper (BeCu)
 Plating: Gold over Nickel

Outline Socket Dimensions



Part Number (Details)

NP352 - 1521 24 - * - *

Series No.

No. of Contact Pins

Design Number

Mark for Positioning Pins

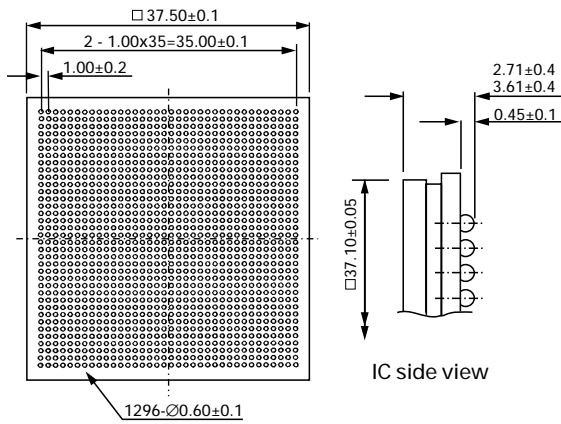
Contact Terminal Lengths and Form

Features

- Open top type sockets with "Tweezer Style Contacts" For FBGA packages
- Secure package alignment due to self contacting structure without upper pressing force (ZIF)
- Contacting structure to nip the sides of solder balls to lower damages of coplanarity of solder balls

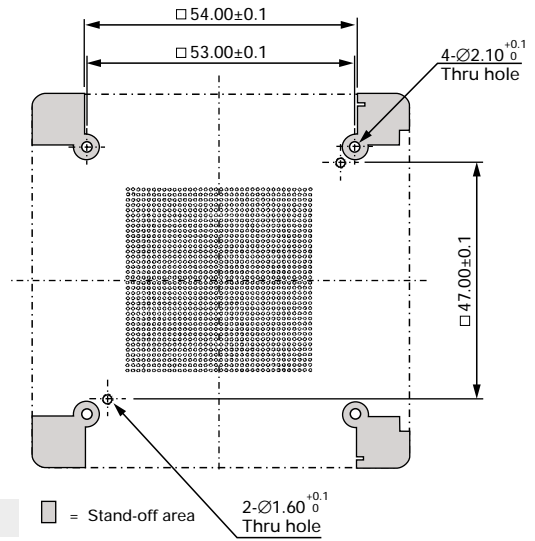
Part Number	Pin Count	IC Dimensions		Socket Dimensions A x B
		Grid Size	Body Size _(mm)	
NP352-1296-52	1296	36 x 36	37.5 x 37.5	74.0 x 74.0
NP352-152124	1521	39 x 39	40 x 40	62.0 x 62.0
NP352-160018	1600	41 x 41	42.5 x 42.5	74.0 x 74.0
NP352-1600-54	1600	40 x 40	45 x 45	74.0 x 74.0
NP352-1849-35	1849	43 x 43	45 x 45	74.0 x 74.0

1296 pins NP352-1296-52

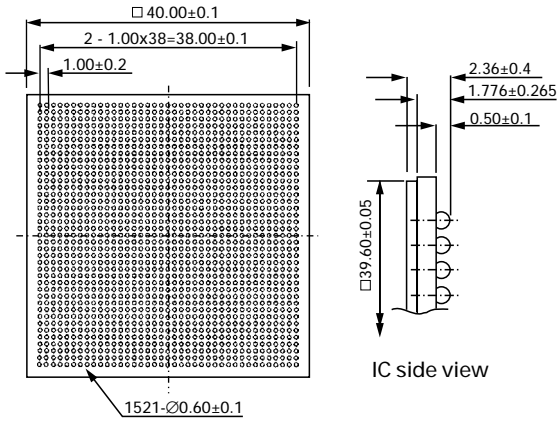


Grid Size 36 x 36

Recommended PCB Layout

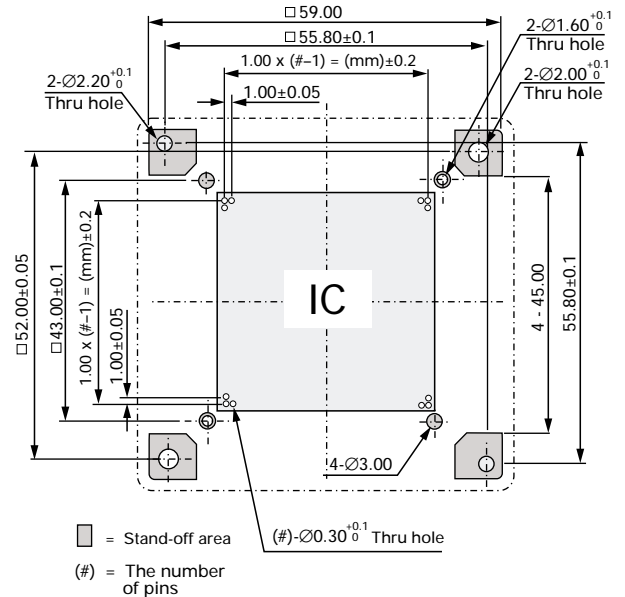


1521 pins NP352-152124

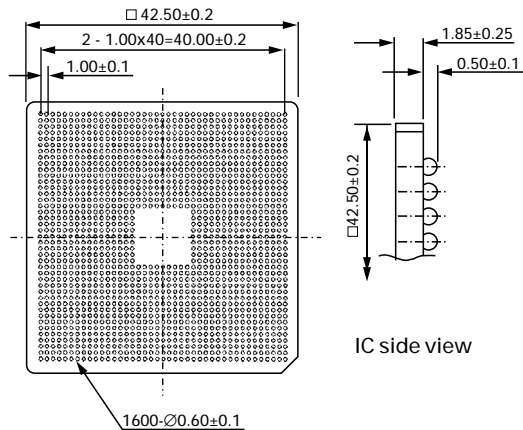


Grid Size 39 x 39

Recommended PCB Layout



1600 pins NP352-160018



Grid Size 41 x 41

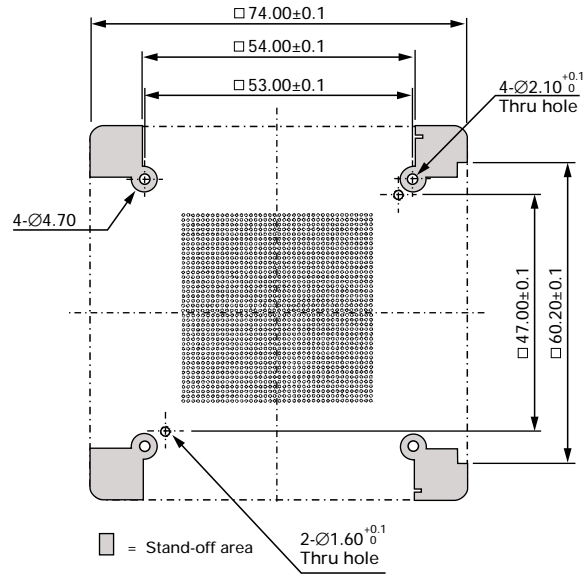
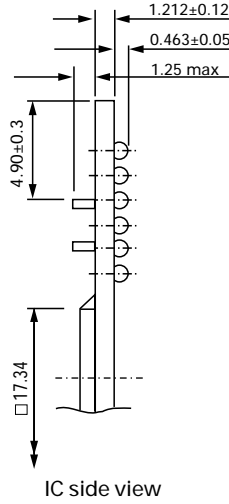
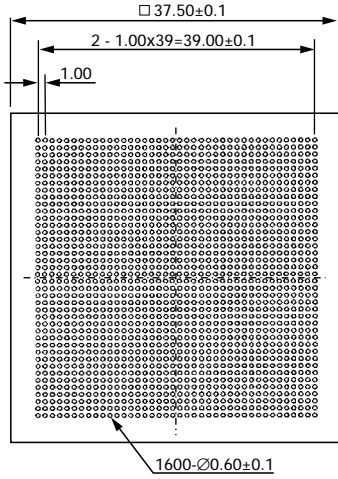
NP352 Series (Open Top)

Fine Ball Grid Array (FBGA, 1.00mm Pitch)

Top View from Socket

1600 pins NP352-1600-54-*

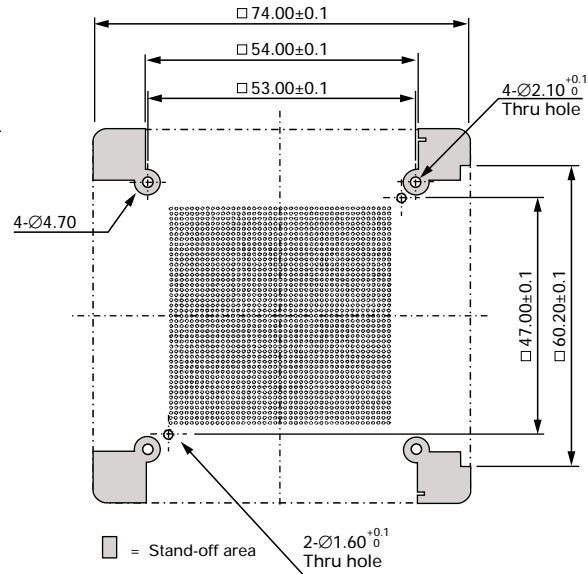
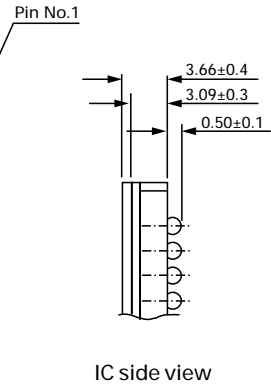
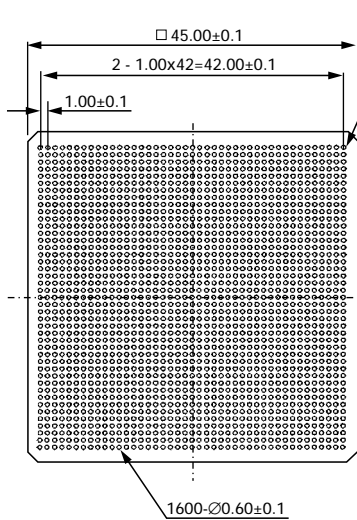
Recommended PCB Layout



Grid Size 40 x 40

1849 pins NP352-1849-35

Recommended PCB Layout



Grid Size 42 x 43